TOSHIBA THYRISTOR SILICON PLANAR TYPE

SF1G53

LOW POWER SWITCHING AND CONTROL APPLICATIONS

Radial Taping

Repetitive Peak Off-State Voltage : V_{DRM} $\Rightarrow =400V$ Repetitive Peak Reverse Voltage

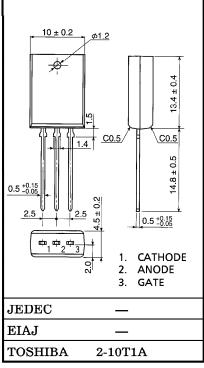
Average On-State Current $: I_{T(AV)} = 1A$

Plastic Mold Type

MAXIMUM RATINGS (Ta = 25°C)

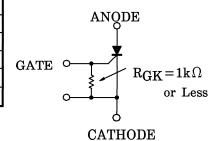
CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Off-State Voltage and Repetitive Peak Reverse Voltage $(R_{GK} = 1k\Omega)$	$v_{ m DRM} \ v_{ m RRM}$	400	V	
Non-Repetitive Peak Reverse Voltage (Non-Repetitive $< 5 \text{ms}$, $R_{GK} = 1 \text{k} \Omega$, $T_j = 0 \sim 125 ^{\circ}\text{C}$)	$v_{ m RSM}$	500	V	
Average On-State Current (Full Sine Waveform Ta=37°C)	I _{T (AV)}	1	A	
R.M.S On-State Current	IT (RMS)	1.57	Α	
Peak One Cycle Surge On-State	Imass	8 (50Hz)	Α	
Current (Non-Repetitive)	ITSM	8.8 (60Hz)	A.	
I ² t Limit Value (t=1~10ms)	${f I}^2{f t}$	0.32	$\mathbf{A}^2\mathbf{s}$	
Peak Gate Power Dissipation	P_{GM}	0.1	W	
Average Gate Power Dissipation	PG (AV)	0.01	W	
Peak Forward Gate Voltage	v_{FGM}	5	V	
Peak Reverse Gate Voltage	v_{RGM}	– 5	V	
Peak Forward Gate Current	I_{GM}	100	mA	
Junction Temperature	$T_{ m j}$	-40~125	$^{\circ}\mathrm{C}$	
Storage Temperature Range	$T_{ m stg}$	-40~125	$^{\circ}\mathrm{C}$	

Unit in mm



Weight: 1.5g

(Note)Should be used with gate resistance as follows.



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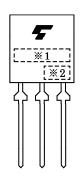
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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current and Repetitive Peak Reverse Current	I _{DRM} I _{RRM}	$V_{DRM} = V_{RRM} = Rated$ $R_{GK} = 1k\Omega$, $T_j = 125$ °C	_	_	200	μ A
Peak On-State Voltage	$V_{ ext{TM}}$	$I_{\text{TM}} = 2A$	_	_	1.7	V
Gate Trigger Voltage	v_{GT}	$V_D = 6V$, $R_L = 100\Omega$, $R_{GK} = 1k\Omega$		_	0.8	V
Gate Trigger Current	I_{GT}	VD-6V, KL-10022, KGK-1K22	_	_	200	μ A
Gate Non-Trigger Voltage	V_{GD}	$V_D = 6V$, $R_{GK} = 1k\Omega$, $T_c = 125$ °C	0.2	_	_	V
Holding Current	$I_{ m H}$	$R_L=100\Omega$, $R_{GK}=1k\Omega$	_	3	_	mA
Thermal Resistance	R _{th (j-a)}	Junction to Ambient	_	_	69	°C/W

MARKING



NUMBER	Ş	SYMBOL	MARK
* 1	TYPE	SF1G53	SF1G53
*2		Starting from Alphabet A Last Decimal Digit of the Current Year	Example 8A: January 1998 8B: February 1998 8L: December 1998

